

**Features**

	$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
$Q_1$	25V	270m $\Omega$ @4.5V	0.8 A
		320m $\Omega$ @2.5V	
		800m $\Omega$ @1.8V	
$Q_2$	-25V	520m $\Omega$ @-4.5V	-0.8 A
		700m $\Omega$ @-2.5V	
		950m $\Omega$ (TYP)@-1.8V	

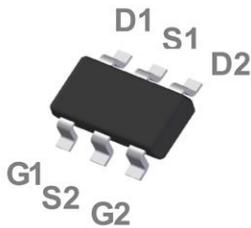
- ESD Protected

**Application**

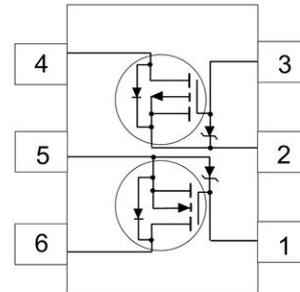
- Notebook
- Load Switch
- Networking
- Hand-held Instruments

**Package and Pin Configuration**

**SOT23-6**



**Circuit diagram**



**Marking: 321P**

**Absolute Maximum Ratings**  $T_c=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
<b>N-MOSFET</b>			
Drain-Source Voltage	$V_{DS}$	25	V
Typical Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current (note 1)	$I_D$	0.8	A
Pulsed Drain Current ( $t_p=10\mu\text{s}$ )	$I_{DM}$	1.3	A
<b>P-MOSFET</b>			
Drain-Source Voltage	$V_{DS}$	-25	V
Typical Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current (note 1)	$I_D$	-0.8	A
Pulsed Drain Current ( $t_p=10\mu\text{s}$ )	$I_{DM}$	-1.3	A
<b>Temperature and Thermal Resistance</b>			
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	140	$^\circ\text{C/W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	$^\circ\text{C}$
Maximum Power Dissipation		0.9	W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

**Q<sub>1</sub>  
N-ch MOSFET ELECTRICAL CHARACTERISTICS**

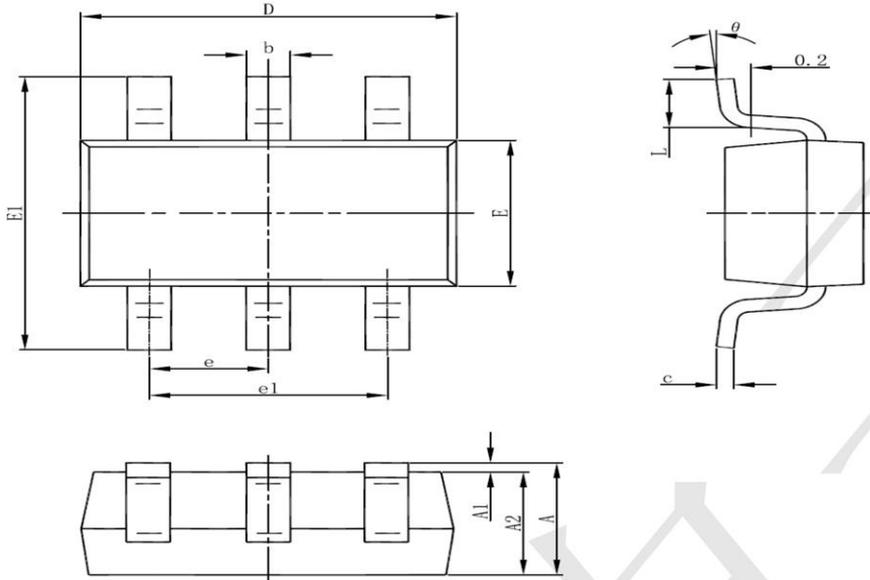
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	25			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> = 0V			±20	uA
Gate threshold voltage (note 2)	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.45	0.7	1.1	V
Drain-source on-resistance(note 2)	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.65A			270	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.55A			320	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =0.45A			800	mΩ
Forward tranconductance(note 2)	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =0.8A		1.6		S
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =0.15A, V <sub>GS</sub> = 0V			1.2	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, f =1MHz			120	pF
Output Capacitance	C <sub>oss</sub>				20	pF
Reverse Transfer Capacitance	C <sub>rss</sub>				15	pF
<b>SWITCHING CHARACTERISTICS (note 3,4)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, I <sub>D</sub> =500mA, R <sub>GEN</sub> =10Ω		6.7		ns
Turn-on rise time	t <sub>r</sub>			4.8		ns
Turn-off delay time	t <sub>d(off)</sub>			17.3		ns
Turn-off fall time	t <sub>f</sub>			7.4		ns

**Q<sub>2</sub>  
P-ch MOSFET ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	-25			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> = 0V			-1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> = 0V			±20	uA
Gate threshold voltage (note 2)	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.45	-0.7	-1.3	V
Drain-source on-resistance(note 2)	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A		270	520	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-0.8A		330	700	mΩ
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-0.5A		950		mΩ
Forward tranconductance(note 2)	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-0.54A		1.2		S
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =-0.5A, V <sub>GS</sub> = 0V			-1.2	V
<b>DYNAMIC CHARACTERISTICS (note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, f =1MHz			170	pF
Output Capacitance	C <sub>oss</sub>				25	pF
Reverse Transfer Capacitance	C <sub>rss</sub>				15	pF
<b>SWITCHING CHARACTERISTICS (note 3,4)</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-10V, I <sub>D</sub> =-200mA, R <sub>GEN</sub> =10Ω		9		ns
Turn-on rise time	t <sub>r</sub>			5.8		ns
Turn-off delay time	t <sub>d(off)</sub>			32.7		ns
Turn-off fall time	t <sub>f</sub>			20.3		ns



SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [MOSFET](#) category:*

*Click to view products by [TECH PUBLIC](#) manufacturer:*

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [NTNS3A92PZT5G](#) [IRFD120](#) [IRFF430](#) [JANTX2N5237](#) [2N7000](#) [AOD464](#)  
[2SK2267\(Q\)](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [SSM6J414TU,LF\(T](#) [751625C](#)  
[IPS70R2K0CEAKMA1](#) [BSF024N03LT3 G](#) [PSMN4R2-30MLD](#) [TK31J60W5,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#)  
[EFC2J004NUZTDG](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [NTE2969](#) [NTE6400A](#) [DMC2700UDMQ-7](#)  
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [SSM6P54TU,LF](#) [DMP22D4UFO-7B](#) [IPS60R3K4CEAKMA1](#)  
[DMN1006UCA6-7](#) [DMN16M9UCA6-7](#) [STF5N65M6](#) [IRF40H233XTMA1](#) [IPSA70R950CEAKMA1](#) [IPSA70R2K0CEAKMA1](#) [STU5N65M6](#)  
[C3M0021120D](#) [DMN6022SSD-13](#)